

1. (Amended) A device for cooling electronics comprising

(a) a container having a receptacle for receiving an electronic device, the container defining a chamber that is partially filled with a liquid coolant, wherein the receptacle is disposed between the electronic device and the chamber; the container also being capable of receiving a cooling conduit;

(b) a wick structure positioned within the container.

10. (Amended) A method for cooling electronics comprising:

(a) providing a container having a receptacle for receiving an electronic device, the container defining a chamber and having an inner wall and an outer wall;

(b) filling the container partially with a liquid coolant such that the liquid coolant does not contact both the inner wall and the outer wall simultaneously;

(c) providing an electronic device;

(d) connecting the electronic device to the receptacle of the container, wherein the receptacle is disposed between the electronic device and the chamber;

(e) generating heat by the electronic device;

(f) transferring heat to the coolant;

(g) connecting a cooling conduit to the container;

(h) forcing air or liquid through the cooling conduit.